



PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Teck Kheng Lee

Serial No.: 10/782,270

Filed: February 18, 2004

For: INTERPOSER SUBSTRATE AND
WAFER SCALE INTERPOSER
SUBSTRATE MEMBER FOR USE WITH
FLIP-CHIP CONFIGURED
SEMICONDUCTOR DICE

Confirmation No.: 4215

Examiner: J. Clark

Group Art Unit: 2815

Attorney Docket No.: 2269-4973.1US

Notice of Allowance Mailed:

January 26, 2006

NOTICE OF EXPRESS MAILING

Express Mail Mailing Label Number: EL995987189US

Date of Deposit with USPS: April 26, 2006

Person making Deposit: Timothy Palfreyman

TRANSMITTAL LETTER

Mail Stop Issue Fee
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

Applicant submits herewith Part B - Fee(s) Transmittal for the above-captioned application and a check in the amount of \$1715 in payment therefor plus five (5) copies of the patent when issued.

Also, enclosed is an Amendment Pursuant to 37 C.F.R. § 1.312(a) (23 pages); Comments on Statement of Reasons for Allowance (2 pages); and Fee Addressee for Receipt of PTO Notices Relating to Maintenance Fees (2 pages).

Applicant understands that no additional fees are required. However, if the Office determines that any comparison fees or other additional fees are required, the Commissioner is authorized to charge any such fees to TraskBritt Deposit Account No. 20-1469. A copy of this Transmittal Letter is enclosed for deposit account charging purposes.

Respectfully submitted,



Bradley B. Jensen
Registration No. 46,801
Attorney for Applicant
TRASKBRITT
P.O. Box 2550
Salt Lake City, Utah 84110-2550
Telephone: 801-532-1922

Date: April 26, 2006

BBJ/dn:slm

Enclosures: Part B - Issue Fee Transmittal (1 page)
Check No. 22777 in the amount of \$1715
Copy of Transmittal Letter (2 pages)
Amendment Pursuant to 37 C.F.R. § 1.312(a) (23 pages)
Comments on Statement of Reasons for Allowance (2 pages)
Fee Addressee for Receipt of PTO Notices Relating to Maintenance Fees (2 pages)

Document in ProLaw



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COMMENTS ON STATEMENT OF REASONS FOR ALLOWANCE

Mail Stop ISSUE FEE
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

In the Office Action dated September 22, 2004, the Examiner indicates:

The applied reference fails to teach and/or suggest the limitations as set forth in claim 14.

Applicants concur with the reasons as stated by the Examiner insofar as they comprise a summary, and are exemplary and not limiting. However, Applicants note that the scope of the claims must be determined from the literal language of each claim as a whole, as well as equivalents thereof.

Respectfully submitted,



Bradley B. Jensen
Registration No. 46,801
Attorney for Applicant
TRASKBRITT
P.O. Box 2550
Salt Lake City, Utah 84110-2550
Telephone: 801-532-1922

Date: April 26, 2006

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